



2811

Atty. Dkt. No. 039153-0457 (G1162)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#9 / Supp
185
9-22-03
Retains

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY
COPPER ALLOY TO OBTAIN A
LOW RESISTANCE AND LARGE
GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Magee, Thomas J.

Art Unit: 2811

<p align="center">CERTIFICATE OF MAILING</p> <p>I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, Virginia 22313-1450, on the date below.</p> <p><u>Deborah A. Kocorowski</u> (Printed Name)</p> <p><u>Deborah A. Kocorowski</u> (Signature)</p> <p><u>6-24-03</u> (Date of Deposit)</p>
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STATEMENT PURSUANT TO 37 C.F.R. §1.97(e)(1)

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Sir:

Pursuant to 37 C.F.R. §1.97(e)(1), the undersigned Attorney of record hereby states that each item of information contained in the Supplemental Information Disclosure Statement filed herewith was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Supplemental Information Disclosure Statement.

Respectfully submitted,

Date June 24, 2003

FOLEY & LARDNER
Suite 3800
777 East Wisconsin Avenue
Milwaukee, Wisconsin 53202-5306
Telephone: (414) 297-5728
Facsimile: (414) 297-4900

By

Paul S. Hunter
Paul S. Hunter
Attorney for Applicant
Registration No. 44,787